



# SOT427

Plastic single-ended surface-mounted package (D2PAK-7); 7 leads (one lead cropped)

7 June 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	S (single)
<b>Package type descriptive code</b>	D2PAK-7
<b>Package type industry code</b>	D2PAK-7
<b>Package style descriptive code</b>	SMS (surface-mounted single in-line)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	16-3-2006

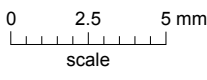
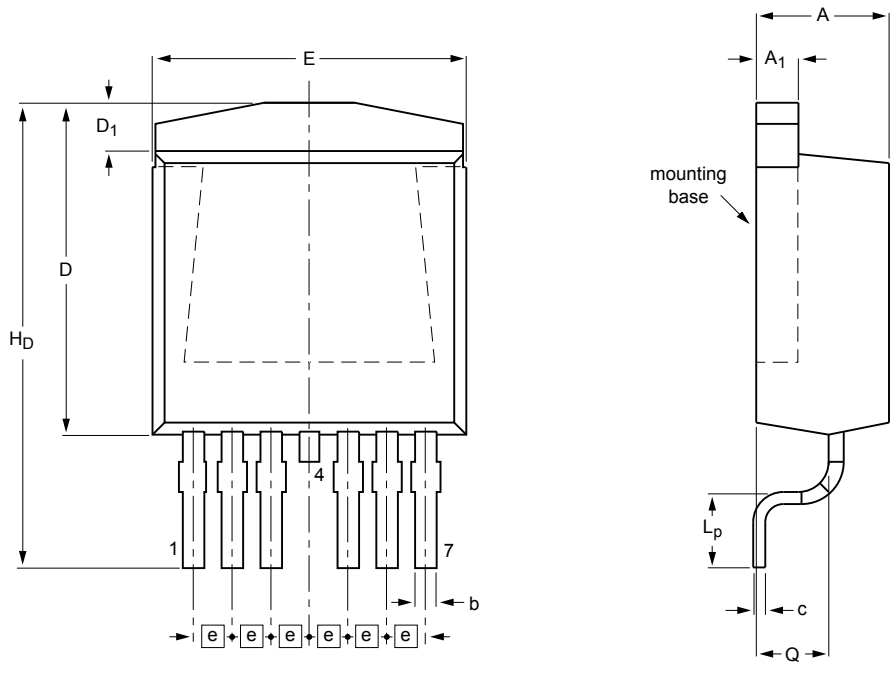
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	11	11	mm
E	package width	9.7	-	10	10.3	mm
A	seated height	4.1	-	4.3	4.5	mm
A <sub>2</sub>	package height	-	-	-	-	
e	nominal pitch	-	-	1.27	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	7	-	



## 2. Package outline

Plastic single-ended surface-mounted package (D2PAK-7); 7 leads (one lead cropped) SOT427



Dimensions (mm are the original dimensions)

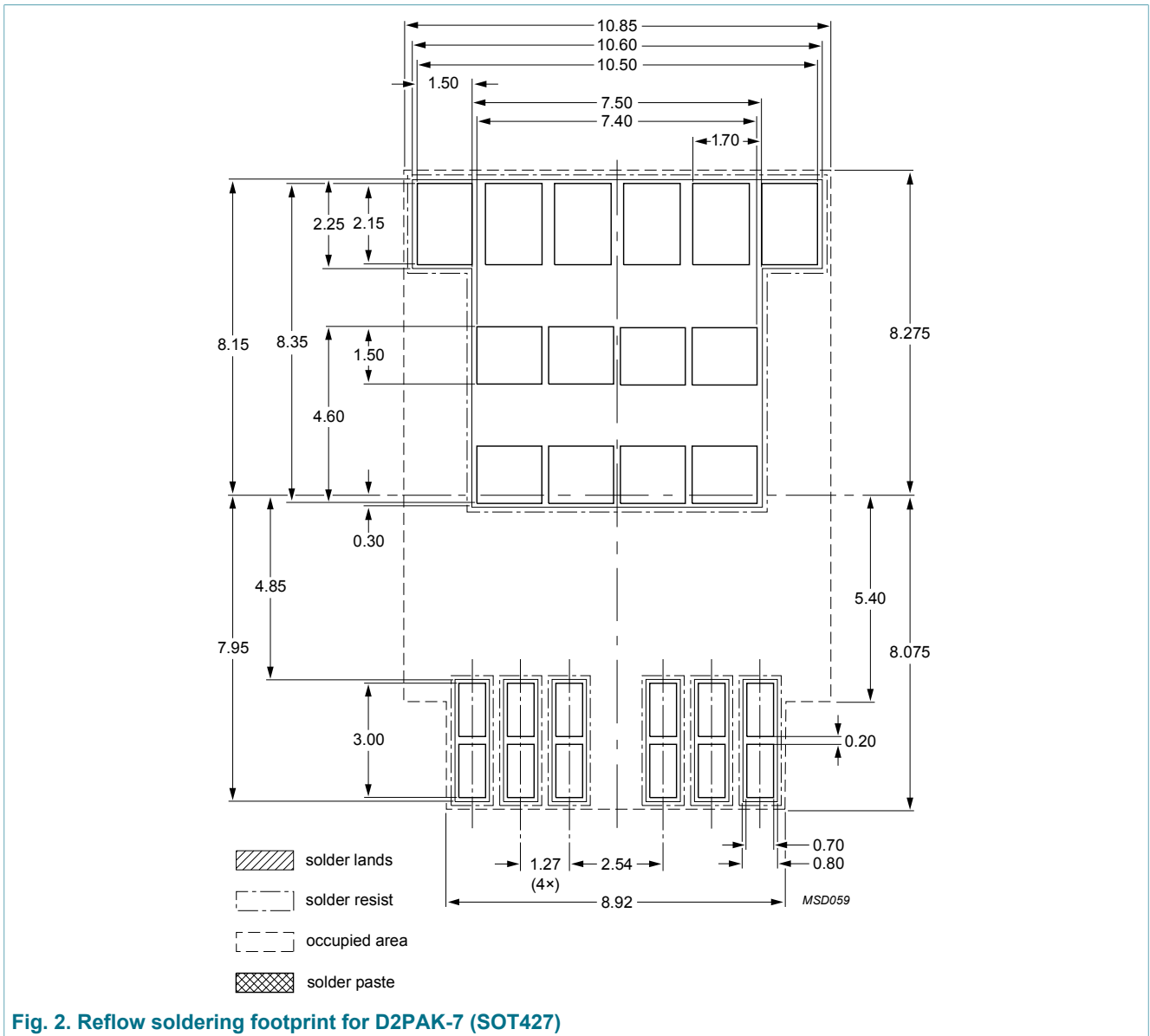
Unit <sup>(1)</sup>	A	A <sub>1</sub>	b	c	D	D <sub>1</sub>	E	e	L <sub>p</sub>	H <sub>D</sub>	Q
max	4.5	1.40	0.85	0.64	11	1.6	10.3		2.90	15.8	2.6
nom								1.27			
min	4.1	1.27	0.60	0.46		1.2	9.7		2.10	14.8	2.2

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT427					-06-03-16- 12-10-16

Fig. 1. Package outline D2PAK-7 (SOT427)

### 3. Soldering



## 4. Legal information

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